

# 深圳市金航标电子有限公司

## 产品技术规格书 SPECIFICATION

产品型号 PART NO:      KH6010-A54
客户料号 CUSTOMER PART NO:
客户确认 CUSTOMER APPROVED BY:
确认日期 APPROVED DATE:

RoHS Compliant Parts

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送样日期 Formed On	产品版本 Document Version ( V1.0 )	

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## 产品规格书版本更改记录

### Version rejigger track record

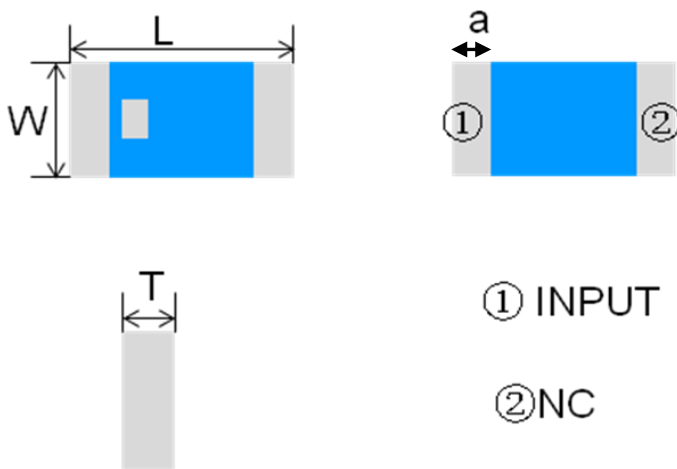
版本号 Version	更改记录 Rejigger	拟制 Prepared	批准 Approve	日期 Date
V1.0	首次发行	姚富鑫	贺俊驹	2018. 12. 11
备注： 1、更改产品电性能指标时，版本号需更换（V1.0 换为 V2.0、V3.0……）； 2、更改产品测试方法（包括可靠性测试条件），或更改使用条件时，当前版本号加系列（V1.0 换为 V1.1、V1.2……）。				

## 1. 概述 INTRODUCTION

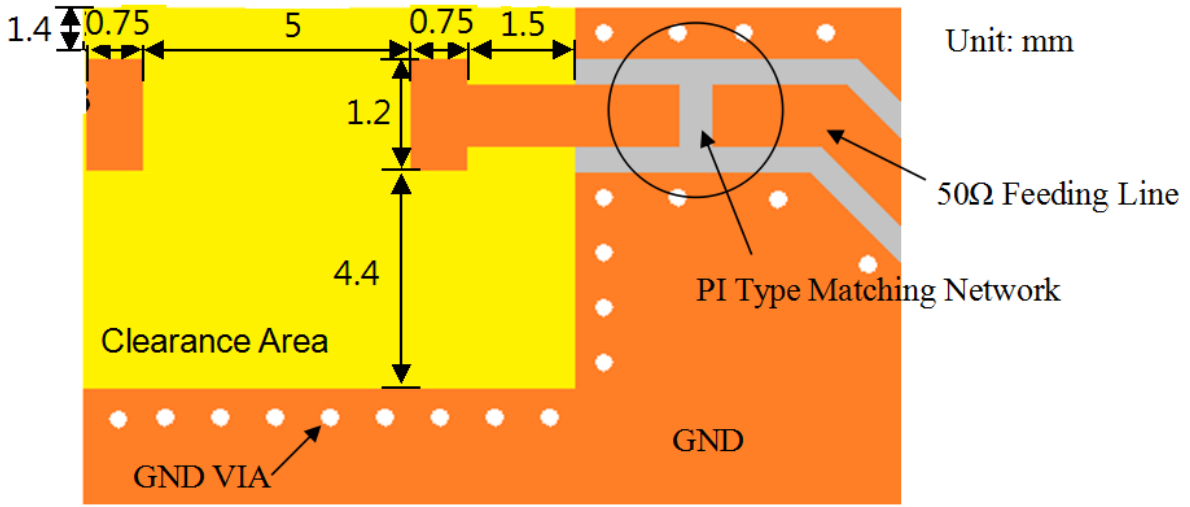
金航标微波多层陶瓷天线 LA 系列产品设计用于 WLAN、WiFi、蓝牙、PHS，手机多频天线, FM 等小体积 SMD 片式设计。

**kinghelm** Microwave Multi-Layer Ceramic Antenna LA series are designed to be used in WLAN、WiFi、Bluetooth、PHS、 Multiple-band Mobile phone antenna, FM, etc and compact size SMD chip design.

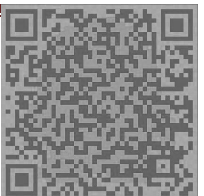
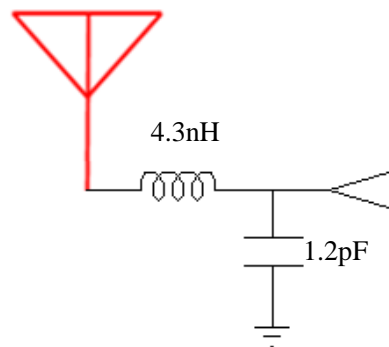
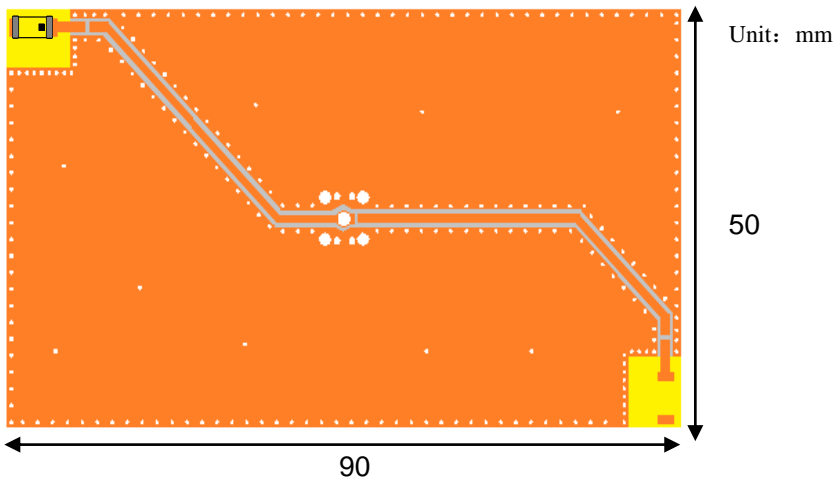
## 2. 外型尺寸及测试板焊盘尺寸 Dimension



Symbol	L	W	T	a
Dimension (mm)	6.0±0.20	1.0±0.20	1.0±0.10	0.5±0.10



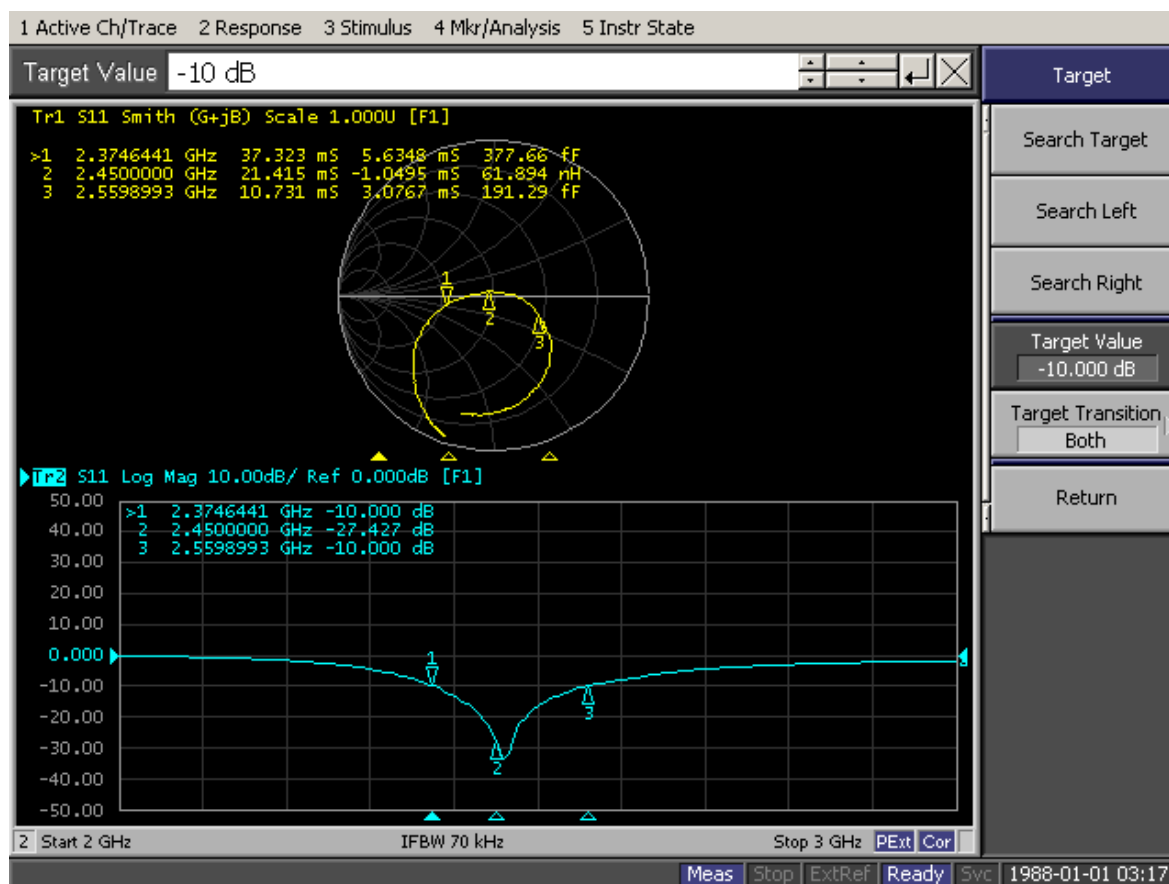
### 3. 测试电路和匹配电路 Evaluation Board and Matching Circuits



## 4. 电气性能 Electrical Characteristics

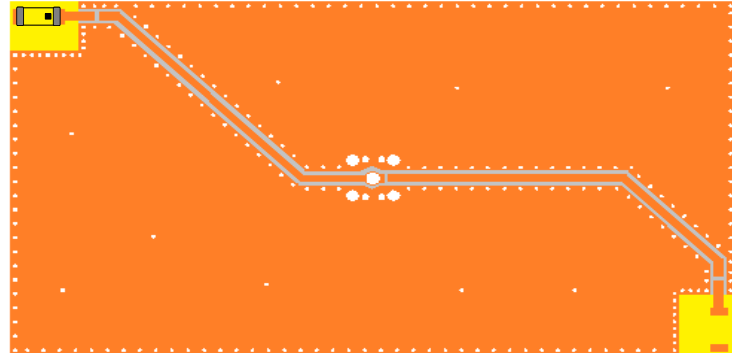
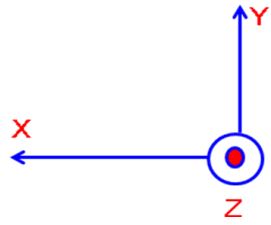
No.	Item (项目)	Specifications (特性)
5.1	Central Frequency 中心频率(No matching)	2670MHz
	(带匹配电路测试)After Matching	2450 MHz
5.2	Band Width 通带宽度	100MHz typ.
5.3	Peak Gain 峰值增益	3.20 dBi
5.4	V.S.W.R 驻波比	$\leq 2.0$
5.5	Polarization 极化方式	Linear 线性
5.6	Azimuth Beam width 方位角	Omni-directional 全向
5.7	Impedance 阻抗	50 $\Omega$

## 5. 特性曲线 Characteristic curve

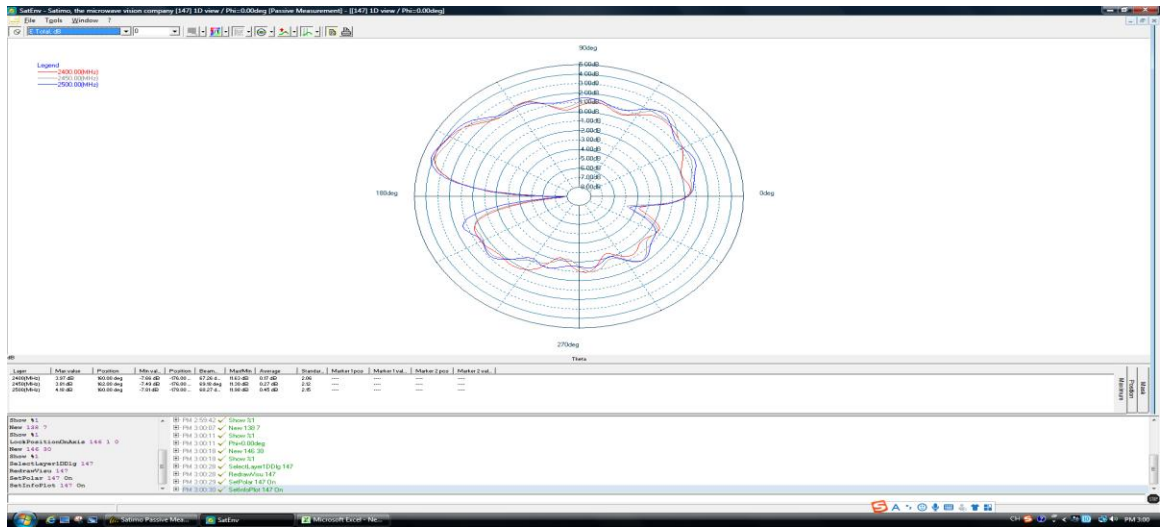


## 6. 方向图及效率 Radiation Pattern & Efficiency

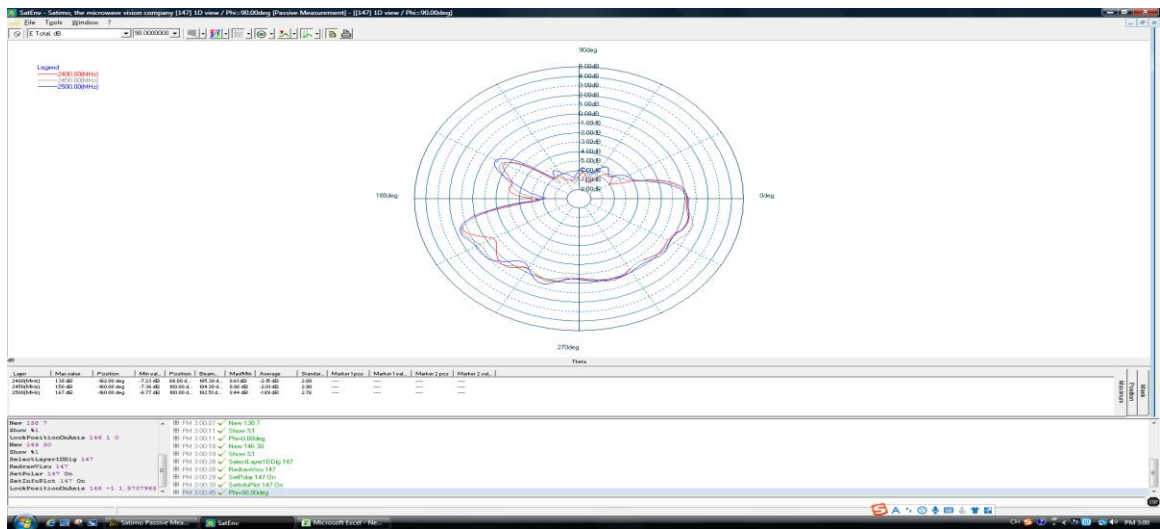
coordinates:



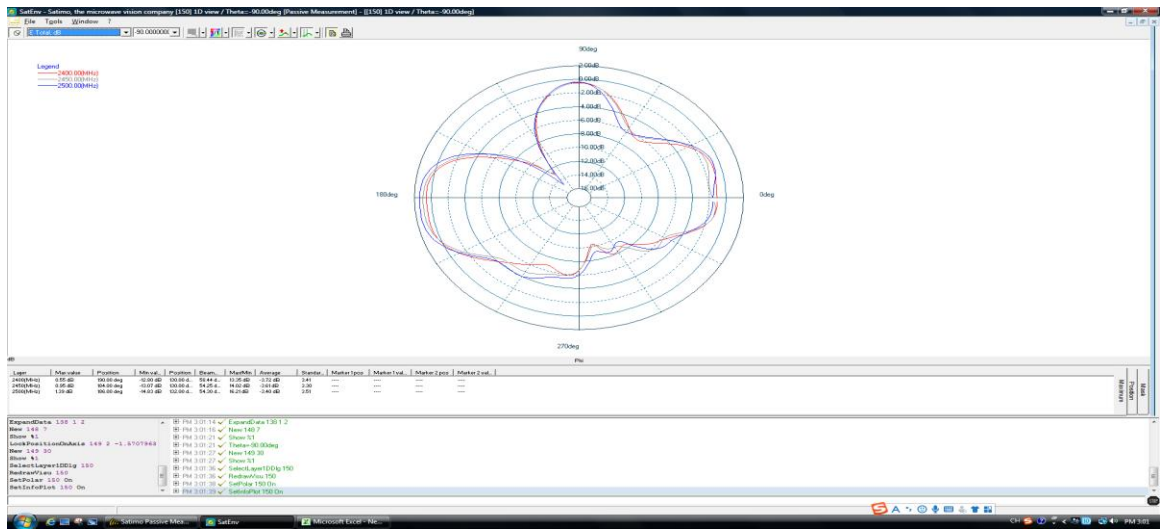
### X-Z Plane



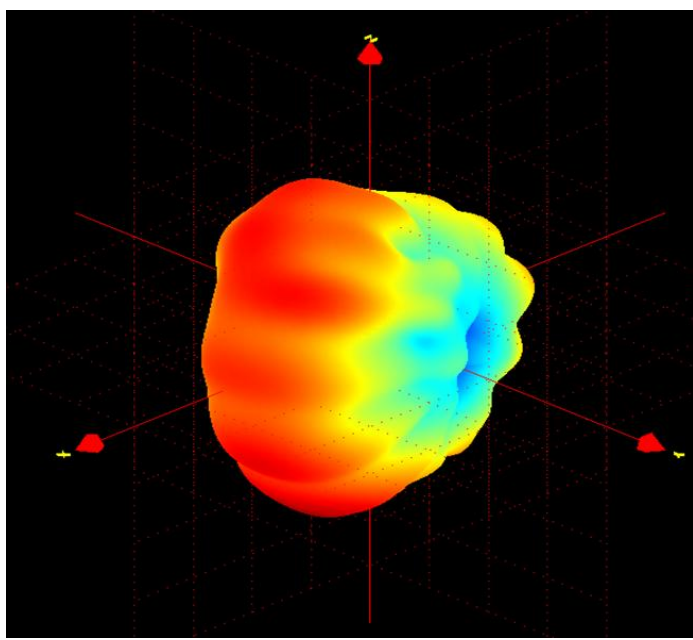
### Y-Z Plane



### X-Y Plane



### 3D Radiation Pattern



Frequency (MHz)	2400	2450	2500
Avg. Gain (dBi)	-1.90	-1.81	-1.61
Peak Gain (dBi)	2.97	3.20	3.41
Efficiency (%)	70.3	72.2	75.4



## 7. 可靠性试验后允许误差 Post Dependability Tolerance

经可靠性试验后允许比起始读数偏差见下表

Post Dependability Tolerance (Refer to the table)

No.	Item (项目)	Post Dependability Tolerance (可靠性试验后允许附加误差)
7.1	Central Frequency 中心频率	±5 MHz
7.2	Band Width 通带宽度	±5 MHz
7.3	Gain 增益	±0.1 dBi
7.4	V.S.W.R (in BW) 驻波比	±0.1

## 8. 可靠性试验 Dependability Test

基准条件: 温度范围 Temperature range  $25 \pm 5^{\circ}\text{C}$   
相对湿度范围 Relative Humidity range 55~75%RH  
工作温度 Operating Temperature range  $-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$

### 8.1 耐振动 Vibration Resist

在振动频率为 10~55Hz 振幅为 1.5mm 沿 X.Y.Z 方向各振动 2 小时后测试符合表 8.1~8.4 规定。

The device should satisfy the electrical characteristics specified in paragraph 8.1~8.4 after applied to the vibration of 10 to 55Hz with amplitude of 1.5mm for 2 hours each in X, Y and Z directions.

### 8.2 耐跌落冲击 Drop Shock

在 100cm 高度处按 X, Y, Z 三个面分别自由跌落在木制地板上共 3 次后测试符合表 8.1~8.4 规定。

The device should satisfy the electrical characteristics specified in paragraph 8.1~8.4 after dropping onto the hard wooden board from the height of 100cm for 3 times each facet of the 3 dimensions of the device.

### 8.3 耐焊接热 Solder Heat Proof

能承受经 120~150°C 的温度预热 120 秒后, 在 255°C+10°C 的焊锡浸 5±0.5 秒, 或 300°C-10°C 的电烙铁焊接 3±0.5 秒, 焊接面无损伤。

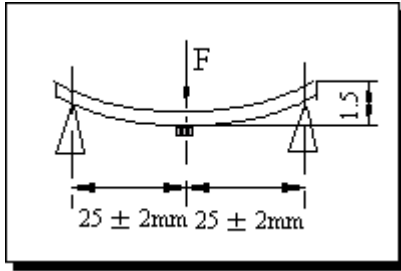
The device should be satisfied after preheating at 120°C~150°C for 120 seconds and dipping in soldering Sn at 255°C+10°C for 5±0.5 seconds, or electric iron 300°C-10°C for 3±0.5 seconds, without damage.

### 8.4 推力试验 Adhesive Strength of Termination

在产品电极端子上或表面上可承受 5N(≤0603); 10N(>0603) 水平推力 10±1 秒而无明显外观损坏与电极移位。

The device have no remarkable damage or removal of the termination after horizontal force of 5N(≤0603); 10N(>0603) with 10±1 seconds.

## 8.5 耐弯曲试验 Bending Resist Test



将产品按图焊在  $1.6 \pm 0.2\text{mm}$  的 PCB 板中间，由箭头方向施力： $1\text{mm/S}$ ，弯曲距离： $1.5\text{mm}$ ，保持  $5 \pm 1\text{S}$ ，产品金属层无脱落。

Weld the product to the center part of the PCB with the thickness  $1.6 \pm 0.2\text{mm}$  as the illustration shows, and keep exerting force arrow-ward on it at speed of  $1\text{mm/S}$ , and hold for  $5 \pm 1\text{S}$  at the position of  $1.5\text{mm}$  bending distance, so far, any peeling off of the

product metal coating should not be detected.

## 8.6 耐湿热特性 Moisture Proof

在温度为  $60 \pm 2^\circ\text{C}$ ，相对湿度  $90\sim 95\%$  的恒温湿箱中放置 96 小时，在常温中恢复 1~2 小时后测试，符合表 8.1~8.4 规定。

The device should satisfy the electrical characteristics specified in paragraph 8.1~8.4 after exposed to the temperature  $60 \pm 2^\circ\text{C}$  and the relative humidity  $90\sim 95\%$  RH for 96 hours and 1~2 hours recovery time under normal condition.

## 8.7 高温特性 High Temperature Endurance

在温度为  $85 \pm 5^\circ\text{C}$  的恒温箱中放置  $96 \pm 2$  小时，在常温中恢复 1~2 小时后测试。符合表 8.1~8.4 规定。

The device should satisfy the electrical characteristics specified in paragraph 8.1~8.4 after exposed to temperature  $85 \pm 5^\circ\text{C}$  for  $96 \pm 2$  hours and 1~2 hours recovery time under normal temperature.

## 8.8 低温特性 Low Temperature Endurance

在温度为  $-40^\circ\text{C} \pm 5^\circ\text{C}$  低温箱中放置  $96 \pm 2$  小时后恢复 1~2 小时测试符合表 8.1~8.4 规定。

The device should also satisfy the electrical characteristics specified in paragraph 8.1~8.4 after exposed to the temperature  $-40^\circ\text{C} \pm 5^\circ\text{C}$  for  $96 \pm 2$  hours and to 2 hours recovery time under normal temperature.

## 8.9 温度循环 Temperature Cycle Test

在  $-40^\circ\text{C}$  温度中保持 30 分钟，再在  $+85^\circ\text{C}$  温度中保持 30 分钟，共循环 5 次后在常温中恢复 1~2 小时后测试符合表 8.1~8.4 规定。

The device should also satisfy the electrical characteristics specified in paragraph 8.1~8.4 after exposed to the low temperature  $-40^\circ\text{C}$  and high temperature  $+85^\circ\text{C}$  for  $30 \pm 2$  min each by 5 cycles and 1 to 2 hours recovery time under normal temperature.

## 9. 回流焊温度 Reflow Soldering Standard Condition

